

In the claims:

Please cancel claims 1-7 and amend claims 8-10 as follows:

Claims 1-7 (canceled).

Claim 8 (currently amended). A fumed silica abrasive ~~useful~~ for polishing tungsten and titanium on a semiconductor wafer wherein the fumed silica has a surface area of greater than  $90 \text{ m}^2/\text{g}$  and has been entirely dispersed and diluted in an acidic pH solution.

Claim 9 (currently amended). The fumed silica abrasive of claim 8 wherein the fumed silica has a surface area greater than  $130 \text{ m}^2/\text{g}$ .

Claim 10 (currently amended). A composition ~~useful~~ for polishing tungsten and titanium on a semiconductor wafer, the composition containing an abrasive, wherein the abrasive is fumed silica abrasive that has a surface area of greater than  $90 \text{ m}^2/\text{g}$  and has been entirely dispersed and diluted in an acidic pH solution.